

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary



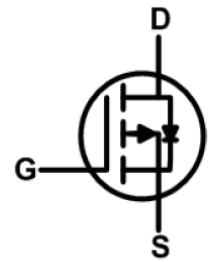
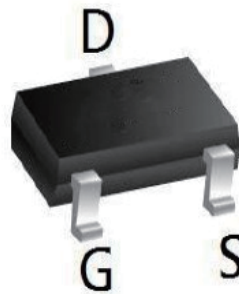
BVDSS	R _{DS(on)}	I _D
-20V	13mΩ	-9.0A

Description

The 20P09L is the high cell density trenched P-ch MOSFETs, which provide excellent R_{DS(on)} and efficiency for most of the small power switching and load switch applications.

The 20P09L meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

SOT23-3L Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
V _{DS}	Drain-to-Source Voltage	-20	V
V _{GS}	Gate-to-Source Voltage	±12	V
I _D	Continuous Drain Current	T _C = 25°C	-9
		T _C = 100°C	-4
I _{DM}	Pulsed Drain Current ⁽¹⁾	-66	A
E _{AS}	Single Pulsed Avalanche Energy ⁽²⁾	28.8	mJ
P _D	Power Dissipation	T _C = 25°C	30
R _{θJA}	Thermal Resistance, Junction to Ambient ⁽³⁾	41.6	°C/W
T _J , T _{STG}	Junction & Storage Temperature Range	-55 to 150	°C

Electrical Characteristics (T_J =25 °C unless otherwise specified)

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D = -250μA	-20	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current (T _J = 25°C)	V _{DS} = -20V, V _{GS} =0V,	-	-	-1	μA
I _{DSS}	Zero Gate Voltage Drain Current (T _J = 100°C)	V _{DS} = -20V, V _{GS} =0V,	-	-	-100	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±12V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D = -250μA	-0.4	-0.65	-1	V
R _{DS(on)}	Static Drain-Source onResistance <small>note2</small>	V _{GS} = -4.5V, I _D = -8A	-	13	18	mΩ
		V _{GS} = -2.5V, I _D = -6A	-	17	23	
g _{fs}	Forward Transconductance ⁴	V _{DS} =-4.5V, I _D = -8A	-	36	-	S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = -10V, V _{GS} =0V, f=1.0MHz	-	1630	-	pF
C _{oss}	Output Capacitance		-	211	-	pF
C _{rss}	Reverse Transfer Capacitance		-	187	-	pF
R _g	Gate Resistance	f=1.0MHz	-	10	-	Ω
Q _g	Total Gate Charge	V _{DS} = -10V, I _D = -8A, V _{GS} = -4.5V	-	12	-	nC
Q _{gs}	Gate-Source Charge		-	1.8	-	nC
Q _{gd}	Gate-Drain("Miller") Charge		-	3.2	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{GS} = -4.5V, V _{DD} = -10V, R _G = 3Ω, I _D = -8A	-	17	-	ns
t _r	Turn-on Rise Time		-	25.5	-	ns
t _{d(off)}	Turn-off Delay Time		-	32	-	ns
t _f	Turn-off Fall Time		-	15	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-40	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S = -8A	-	-	-1.2	V

Note :

- 1.Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C.
- 2.The EAS data shows Max. rating . The test condition is V_{DD}= -25V, V_{GS}= -10V, L= 0.1mH, I_{AS}= -24A
- 3.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper, The value in any given application depends on the user's specific board design.
- 4.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
- 5.This value is guaranteed by design hence it is not included in the production test..

Typical Performance Characteristics

Figure 1: Output Characteristics

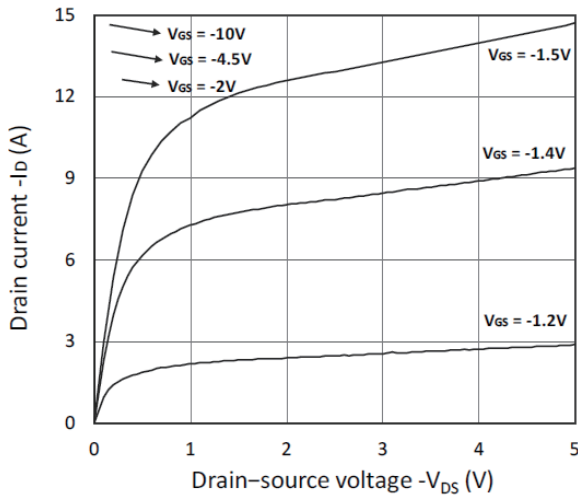


Figure 2: Transfer Characteristics

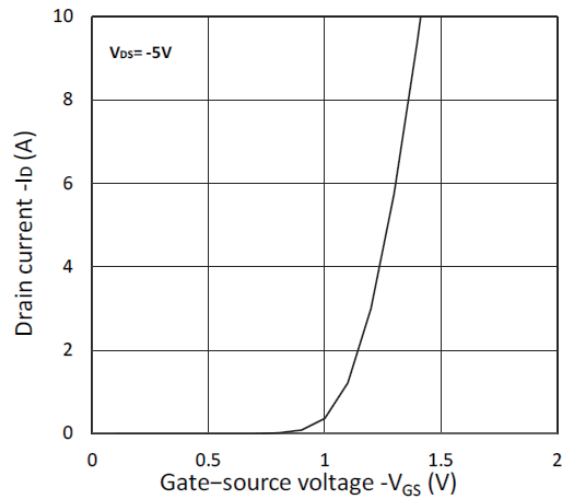


Figure 3: Forward Characteristics of Reverse

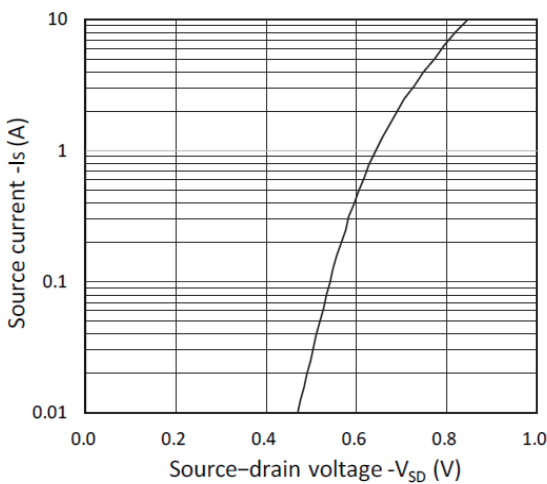


Figure 4: RDS(ON) vs. VGS

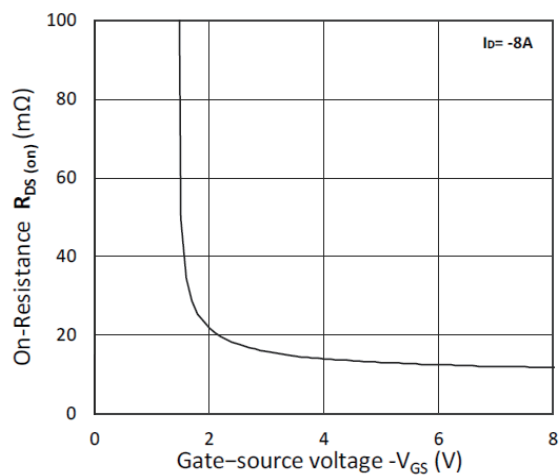


Figure 5: RDS(ON) vs. ID

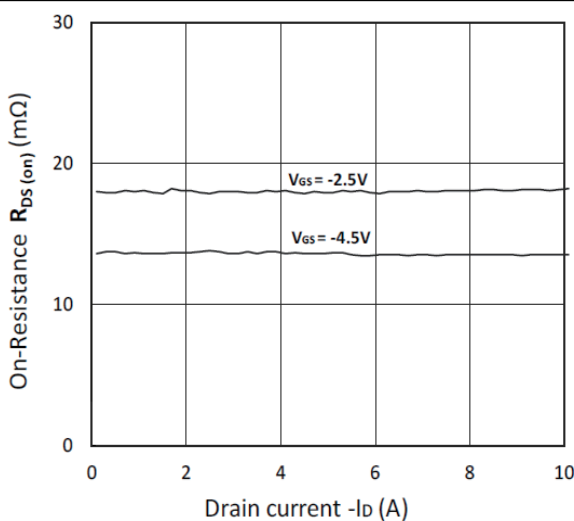
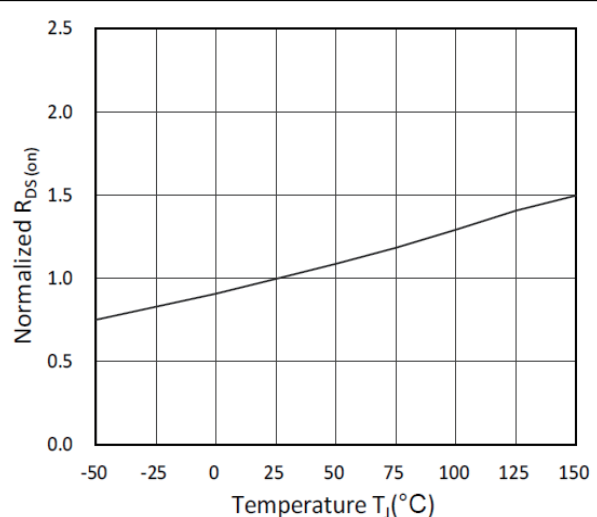


Figure 6: Normalized RDS(on) vs. Temperature



Typical Performance Characteristics

Figure 7: Capacitance Temperature

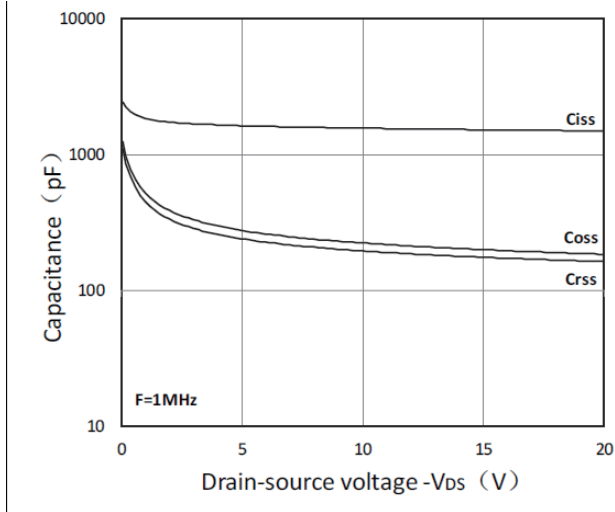


Figure 8: Gate Charge Characteristics

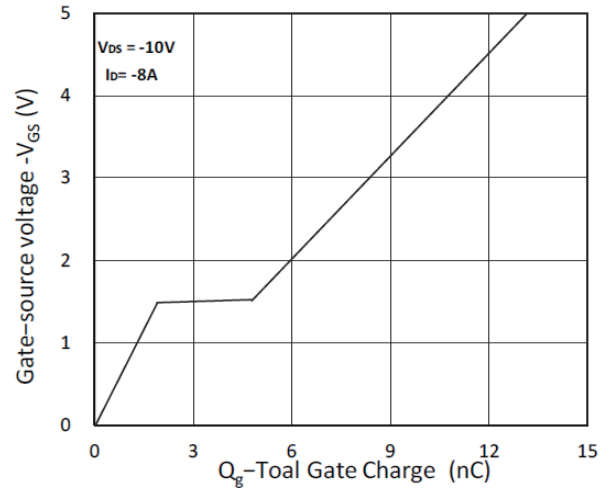


Figure 9: Power Dissipation Thermal Imp

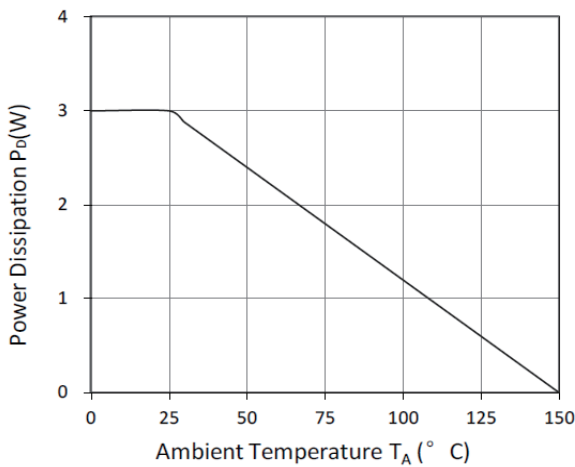


Figure 10: Power Dissipation

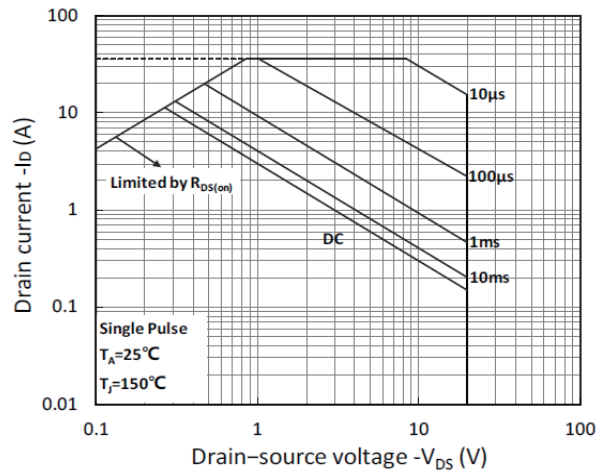
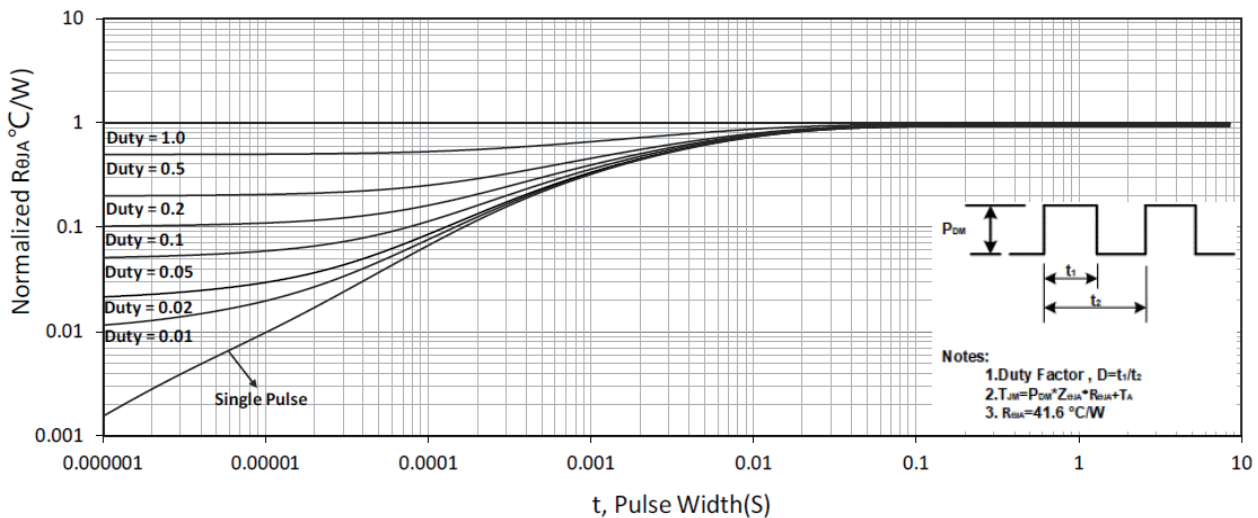
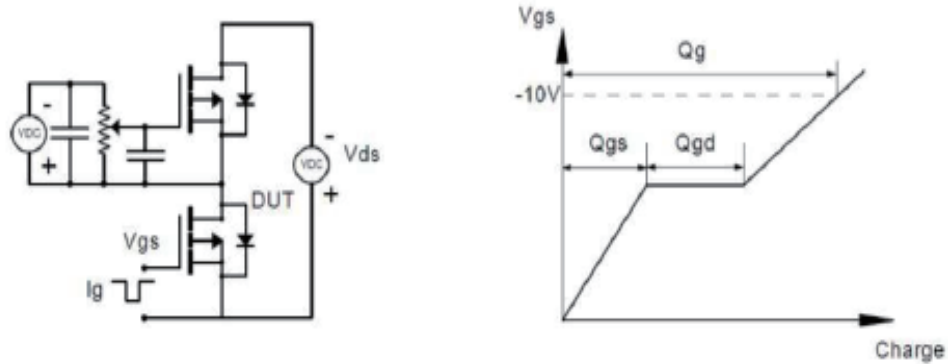


Figure.11: Safe Operating Area

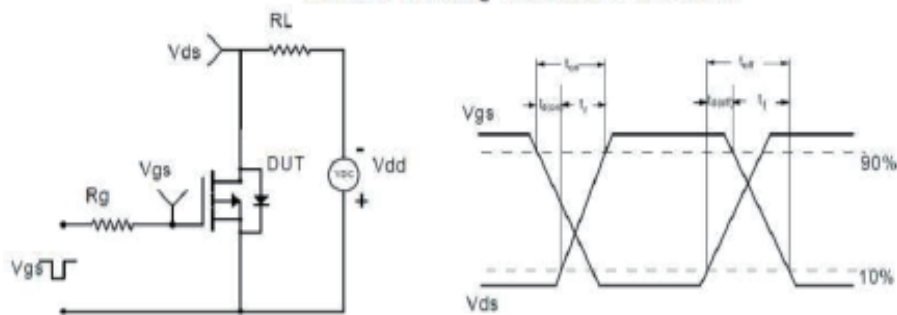


Test Circuit

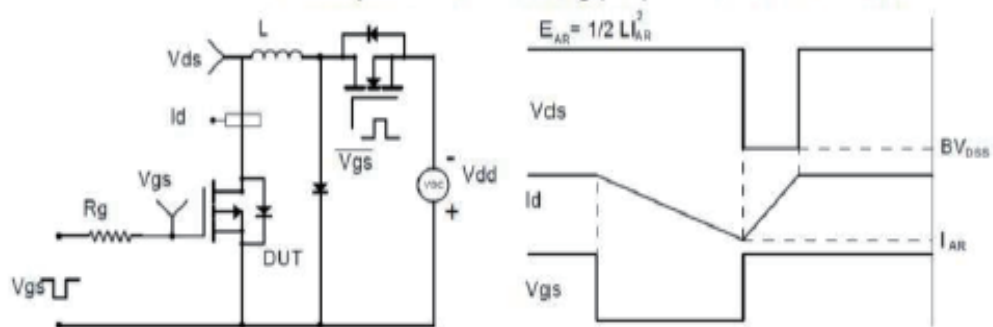
Gate Charge Test Circuit & Waveform



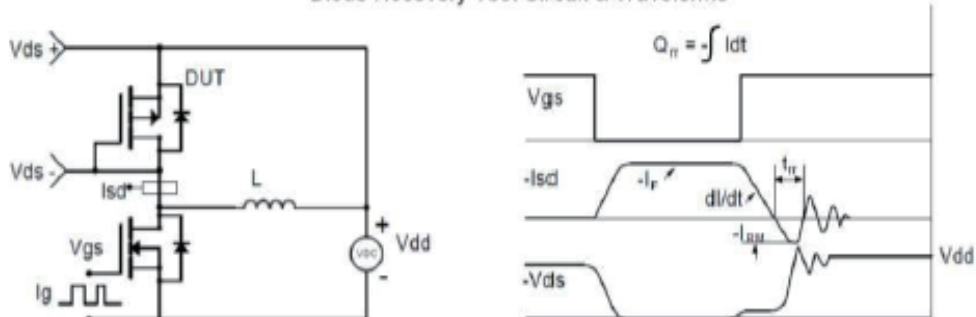
Resistive Switching Test Circuit & Waveforms



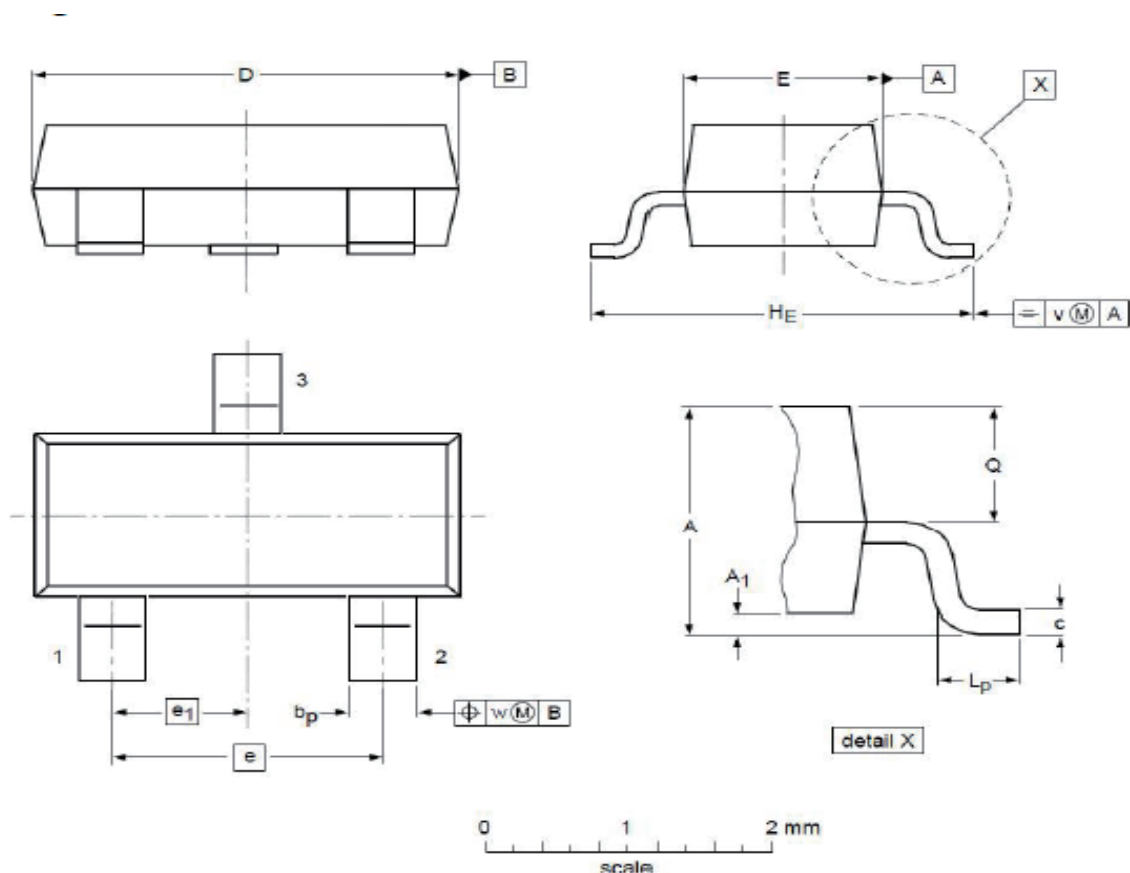
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



SOT-23-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.05	1.25	0.041	0.049
A1	0.00	0.10	0.000	0.004
A2	1.05	1.15	0.041	0.045
b	0.30	0.50	0.012	0.02
c	0.10	0.20	0.004	0.008
D	2.82	3.02	0.111	0.119
E	1.50	1.70	0.059	0.067
E1	2.65	2.95	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
L	0.30	0.60	0.012	0.024
θ	0°	8°	0°	8°

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